ON Semiconductor

Is Now



To learn more about onsemi™, please visit our website at www.onsemi.com

onsemi and ONSEMI. and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. onsemi reserves the right to make changes at any time to any products or information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using onsemi products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by onsemi. "Typical" parameters which may be provided in onsemi data sheets and/ or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. onsemi does not convey any license under any of its intellectual property rights nor the rights of others. onsemi products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use onsemi products for any such unintended or unauthorized application,



ON Semiconductor

FDS4435BZ-F085

P-Channel PowerTrench[®] MOSFET -30V, -8.8A, $20m\Omega$

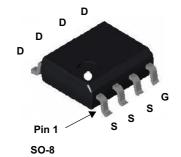
Features

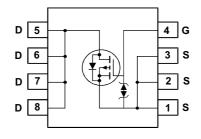
- Max $r_{DS(on)}$ = 20m Ω at V_{GS} = -10V, I_D = -8.8A
- Max $r_{DS(on)}$ = 35m Ω at V_{GS} = -4.5V, I_D = -6.7A
- Extended V_{GSS} range (-25V) for battery applications
- HBM ESD protection level of ±3.8KV typical (note 3)
- High performance trench technology for extremely low r_{DS(on)}
- High power and current handling capability
- Termination is Lead-free and RoHS compliant Qualified to AEC Q101



General Description

This P-Channel MOSFET is produced using ON Semiconductor's advanced PowerTrench® process that has been especially tailored to minimize the on-state resistance. This device is well suited for Power Management and load switching applications common in Notebook Computers and Portable Battery Packs.





MOSFET Maximum Ratings T_A = 25°C unless otherwise noted

Symbol	Param	eter		Ratings	Units
V _{DS}	Drain to Source Voltage			-30	V
V _{GS}	Gate to Source Voltage			±25	V
	Drain Current -Continuous	T _A = 25°C	(Note 1a)	-8.8	^
ID	-Pulsed			-6.6 -50	Α
D	Power Dissipation	T _A = 25°C	(Note 1a)	2.5	W
P_{D}	Power Dissipation	T _A = 25°C	(Note 1b)	1.0	VV
E _{AS}	Single Pulse Avalanche Energy		(Note 4)	24	mJ
T _J , T _{STG}	Operating and Storage Junction Tempera	ature Range		-55 to +150	°C

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case	25	°C/W
$R_{\theta,JA}$	Thermal Resistance, Junction to Ambient (Note	e 1a) 50	C/VV

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDS4435BZ	FDS4435BZ-F085	SO-8	13"	12mm	2500units

Electrical Characteristics T_J = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units			
Off Characteristics									
BV _{DSS}	Drain to Source Breakdown Voltage	$I_D = -250 \mu A, V_{GS} = 0V$	-30			V			
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	I_D = -250 μ A, referenced to 25°C		-21		mV/°C			
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -24V, V_{GS} = 0V$			1	μΑ			
I _{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 25V, V_{DS} = 0V$			±10	μА			

On Characteristics

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = -250 \mu A$	-1	-2.1	-3	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	I _D = -250μA, referenced to 25°C		6		mV/°C
r _{DS(on)}	Static Drain to Source On Resistance	$V_{GS} = -10V, I_D = -8.8A$		16	20	
		$V_{GS} = -4.5V, I_D = -6.7A$		26	35	mΩ
		$V_{GS} = -10V$, $I_D = -8.8A$, $T_J = 125$ °C		22	28	Ī
9 _{FS}	Forward Transconductance	$V_{DS} = -5V, I_{D} = -8.8A$		24		S

Dynamic Characteristics

C _{iss}	Input Capacitance	V _{DS} = -15V, V _{GS} = 0V, f = 1MHz	1385	1845	pF
C _{oss}	Output Capacitance		275	365	pF
C _{rss}	Reverse Transfer Capacitance		230	345	pF
R _g	Gate Resistance	f = 1MHz	4.5		Ω

Switching Characteristics

t _{d(on)}	Turn-On Delay Time		10	20	ns
t _r	Rise Time	V_{DD} = -15V, I_{D} = -8.8A, V_{GS} = -10V, R_{GEN} = 6 Ω	6	12	ns
t _{d(off)}	Turn-Off Delay Time	V _{GS} = -10V, R _{GEN} = 012	30	48	ns
t _f	Fall Time		12	22	ns
Q_g	Total Gate Charge	V _{GS} = 0V to -10V	28	40	nC
Q_g	Total Gate Charge	$V_{GS} = 0V \text{ to } -5V$ $V_{DD} = -15V,$ $I_{D} = -8.8A$	16	23	nC
Q _{gs}	Gate to Source Charge	I _D 0.0A	5.2		nC
Q _{gd}	Gate to Drain "Miller" Charge		7.4		nC

Drain-Source Diode Characteristics

V_{SD}	Source to Drain Diode Forward Voltage	V _{GS} = 0V, I _S = -8.8A (Note 2)	-0.9	-1.2	V
t _{rr}	Reverse Recovery Time	I _F = -8.8A, di/dt = 100A/μs	29	44	ns
Q _{rr}	Reverse Recovery Charge		23	35	nC

NOTES:

^{1.} R_{0,1A} is determined with the device mounted on a 1in² pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. R_{0,1C} is guaranteed by design while R_{0,1C} is determined by the user's board design.



a. 50°C/W when mounted on a 1 in² pad of 2 oz copper.



b. 125°C/W when mounted on a minimum pad of 2 oz copper.

- 2. Pulse Test: Pulse Width < 300μ s, Duty cycle < 2.0%.
- 3. The diode connected between the gate and source serves only as protection against ESD. No gate overvoltage rating is implied.
- 4. Starting T_J = 25°C, L = 1mH, I_{AS} = -7A, V_{DD} = -30V, V_{GS} = -10V

Typical Characteristics $T_J = 25$ °C unless otherwise noted

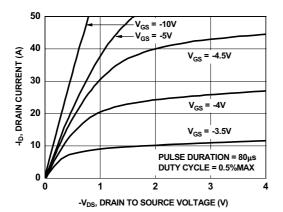


Figure 1. On-Region Characteristics

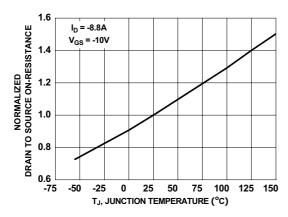


Figure 3. Normalized On-Resistance vs Junction Temperature

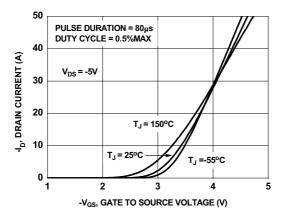


Figure 5. Transfer Characteristics

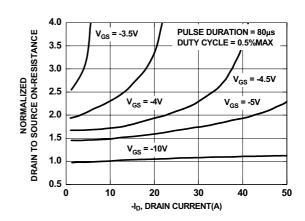


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

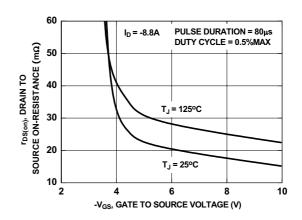


Figure 4. On-Resistance vs Gate to Source Voltage

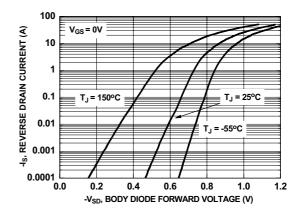


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics $T_J = 25^{\circ}C$ unless otherwise noted

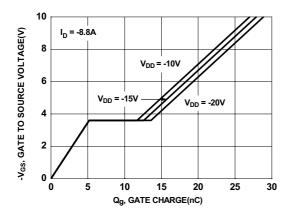


Figure 7. Gate Charge Characteristics

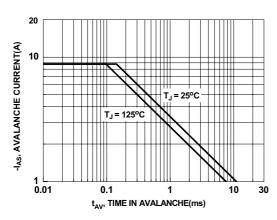


Figure 9. Unclamped Inductive Switching Capability

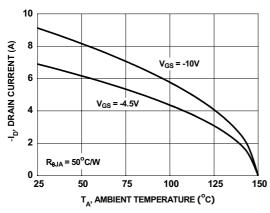


Figure 11. Maximum Continuous Drain Current vs Ambient Temperature

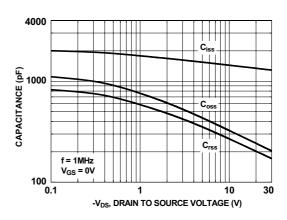


Figure 8. Capacitance vs Drain to Source Voltage

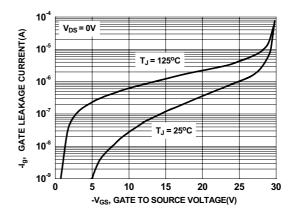


Figure 10. Gate Leakage Current vs Gate to Source Voltage

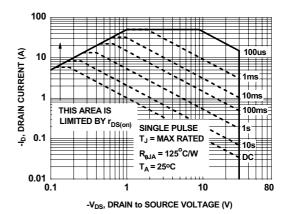


Figure 12. Forward Bias Safe Operating Area



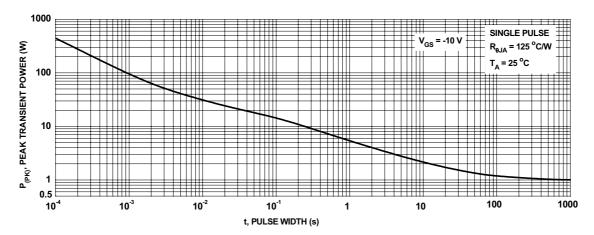


Figure 13. Single Pulse Maximum Power Dissipation

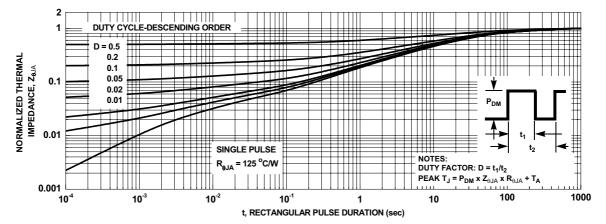


Figure 14. Transient Thermal Response Curve

ON Semiconductor and in are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hol

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800-282-9855 Toll Free USA/Canada
Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910

Phone: 81–3–5817–1050

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative